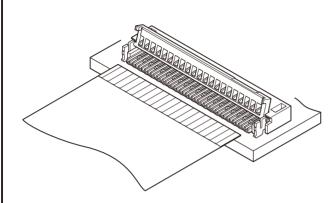


FXZ CONNECTOR



0.3mm pitch/Connectors for FPC



This connector realizes space saving and low profile features demanded by the market, and it provides excellent operability. Various number of circuits can be available.

- Double ZIF design for easy insertion operation of FPC
- Self-lock mechanism enables the cover to close by 'one-touch' operation
- · Versatile number of circuit

Specifications -

• Current rating: 0.2A AC, DC • Voltage rating: 50V AC, DC • Temperature range: -25°C to +85°C

(including temperature rise in applying

electrical current)

• Contact resistance: Initial value/60m Ω max.

After environmental testing/60m Ω max.

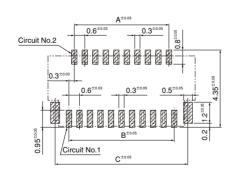
(variation from initial value)

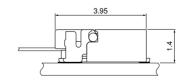
• Insulation resistance: 50M Ω min. Withstanding voltage: 200V AC/minute Applicable FPC: Conductor pitch/0.3mm Conductor width/0.3mm

Mating part thickness/0.2±0.03mm

- * Compliant with RoHS.
- * Refer to "General Instruction and Notice when using Terminals and Connectors" at the end of this catalog.
- Contact JST for details.

PC board layout (viewed from component side) and Assembly layout



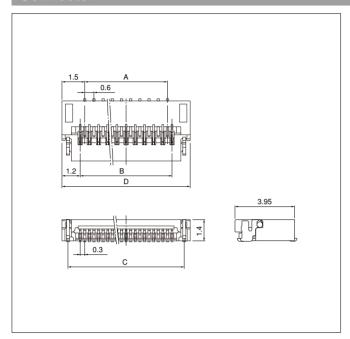


Note: 1. Tolerances are non-cumulative: ±0.05mm for all centers.

2. The dimensions above should serve as a guideline. Contact JST for details.

FXZ CONNECTOR

Connector



Circuits	Model No.	Dimensions (mm)				Q'ty /
		Α	В	С	D	reel
15	15FXZ-RSM1-GAN-ETF	3.6	4.2	5.8	6.6	2,500
17	17FXZ-RSM1-GAN-ETF	4.2	4.8	6.4	7.2	2,500
23	23FXZ-RSM1-GAN-ETF	6.0	6.6	8.2	9.0	2,500
25	25FXZ-RSM1-GAN-ETF	6.6	7.2	8.8	9.6	2,500
29	29FXZ-RSM1-GAN-ETF	7.8	8.4	10.0	10.8	2,500
31	31FXZ-RSM1-GAN-ETF	8.4	9.0	10.6	11.4	2,500
35	35FXZ-RSM1-GAN-ETF	9.6	10.2	11.8	12.6	2,500
39	39FXZ-RSM1-GAN-ETF	10.8	11.4	13.0	13.8	2,500
51	51FXZ-RSM1-GAN-ETF	14.4	15.0	16.6	17.4	2,500
53	53FXZ-RSM1-GAN-ETF	15.0	15.6	17.2	18.0	2,500
61	61FXZ-RSM1-GAN-ETF	17.4	18.0	19.6	20.4	2,500
73	73FXZ-RSM1-GAN-ETF	21.0	21.6	23.2	24.0	2,500

Material and Finish

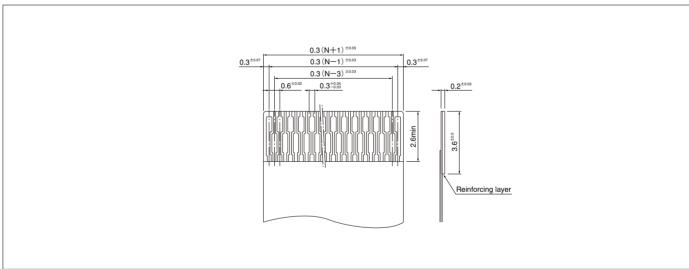
Contact: Copper alloy, nickel-undercoated, gold-plated (nickel-stripe)
Housing: Heat resisting resin, UL94V-0
Solder tab: Copper alloy, copper-undercoated, tin-plated (reflow treatment)
Cover: Heat resisting resin, UL94V-0

RoHS compliance This product displays (LF)(SN) on a label.

Note: 1. This products listed above are supplied on embossed-tape.

2. Contact JST for tin-plated products.

Lead section dimensions of FPC



Note: N --- Number of circuits

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

JST:

 $\frac{33 \text{FXZT-SM1-GAN-TF}}{27 \text{FXZT-SM1-GAN-TF}} \frac{45 \text{FXZT-SM1-GAN-TF}}{45 \text{FXZT-SM1-GAN-TF}} \frac{25 \text{FXZT-SM1-GAN-TF}}{25 \text{FXZT-SM1-GAN-TF}} \frac{31 \text{FXZ-RSM1-G-ETF(LF)}}{31 \text{FXZ-RSM1-G-ETF(LF)}} \frac{31 \text{FXZ$